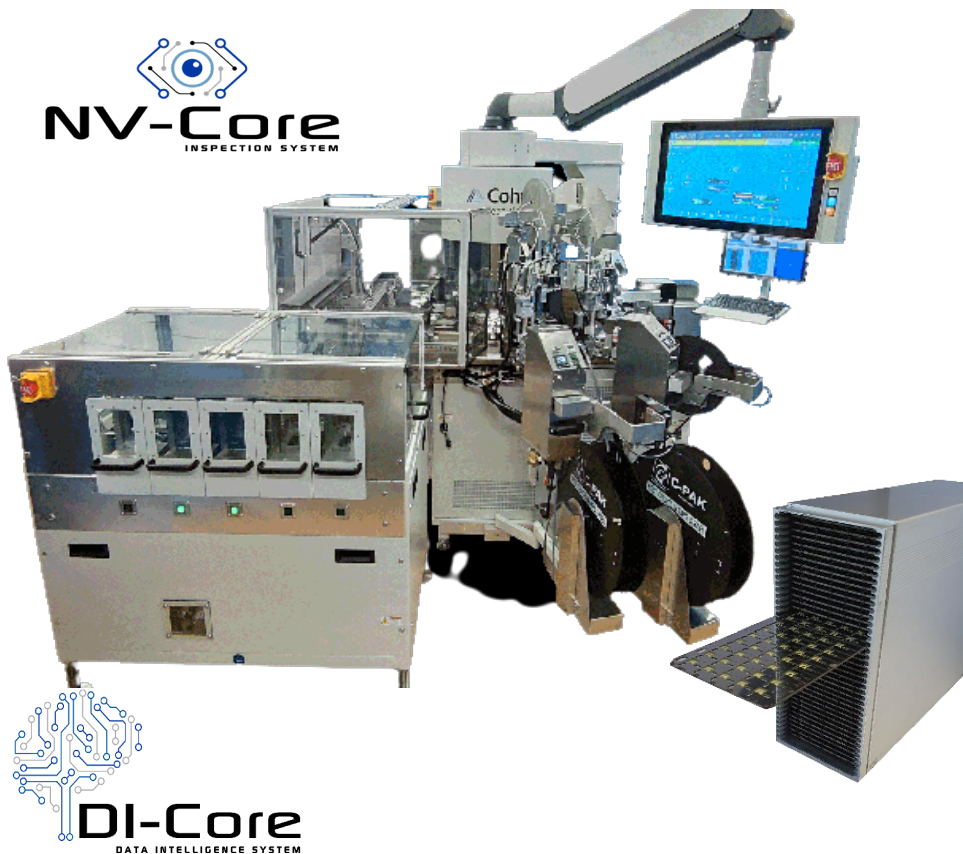


NY32-LU

InCarrier Loader/Unloader



Automotive



Mobility



IoT/loV & Optoelectronics



Computing & Network



Industrial & Medical



Consumer

Productivity

- Up to 12,000 UPH
- Load/Unloading of InCarrier
- Fully secured device process with vision
- Advanced NV-Core Inspection System
- Advanced Force Control Management
- DI-Core Data Intelligence System/ InSight Software

Flexibility

- Tube, Bowl Feeder, Tape and Reel, Tray, Bulk, De-Taper, Wafer
- 6 Sided inspection
- In-Tape inspection with Auto-Reject and Replacement
- Wide applicable device range 0.8 x 0.8 mm to 10 x 10 mm
- Carrier size from 215 x 65 mm to 300 x 100 mm

- Autonomous operation and productivity
- Best-in-class vision and inspection with NV-Core Inspection System
- Load and Unload mode in one system possible

- High device range flexibility
- 100% same spares between Loader and Unloader systems
- Cassette Load/Unload Industry 4.0 Ready

NY32-LU

InCarrier Loader/Unloader

Specification

Platform

Performance Characteristics

- Throughput up to 12,000 UPH. UPH depending on device density per INCC (typical 11,000 with 144 Pockets in Carrier)
- MTBA: Typical >1 hour
- MTBF: Typical >168 hours
- Package conversion time: typical <240 minutes

Device Range per type

- QFN/LGA: 0.8 x 0.8 to 10 x 10 mm
- WLCSP: 0.8 x 0.8 to 10 x 10 mm
- SO: MSOP (118 mil) to TSSOP (300 mil)
- Thickness 0.4 to 5 mm

Devices at and close to spec. limit to be verified

User Interface

- Movable Windows-based color touchscreen
- Language: English and Chinese (simplified), other upon request
- Keyboard, mouse (optional)
- Handler status indicator light (green, yellow, red)
- NV-Core Inspection System: dedicated monitor, keyboard, mouse

Interface

- Network: Ethernet capability
- I/O parallel interface for tester and laser
- SECS GEM (optional)
- GPIB (optional)

ESD

- According to ANSI / ESD S20.0 / ESD SP10.1
- ESD Class 0 (optional)

Facility Requirements

- 110 VAC - 240 VAC 50 Hz/ 60 Hz, one phase
- 2 kVA/ 3.5 kVA with vacuum pump (optional)
- Air pressure range: 5-10 bar \pm 0.5 bar
- Air consumption: 5 m³/hour (typical)
- Vacuum network: -0.5 bars \pm 10%
- Consumption: typical 420 l/min (typical)

Physical Dimensions

- Overall dimension: 2.7 x 2.6 x 1.8 m (max. with tray module)
- Floor space requirement: 3.2 x 3.1 x 1.8 m (max. with tray module)
- Weight: net typical 1,600 kg/gross typical 2,100 kg

Standards

- CE
- SEMI S2/S8 assessment
- 2006/42/EC Machinery
- 2004/108/EC Electromagnetic compatibility (EMC)
- 2006/95/EC Low voltage directive

Process Capabilities

Input

- Bowl, Tube, JEDEC Tray, De-Taping, Wafer

Output

- Tape & Reel, Auto Reel Changer, Tube, Bulk, JEDEC Tray

Processes

- Device orientation
- Device flip
- Test contacting
- Electrical tester (discrete)
- Laser marking
- 6 Sided Vision Inspection
- Bulk, Tube, Dual Tray Sorting
- Waffle Pak sorting
- Wafer map tracability
- DI-Core Data Analytics/InSight Interface

NV-Core Inspection System

- 1D/2DMC code reader
- 2D/3D Flex[®] ball/bump co-planarity
- Mark, Surface, 5S, Color Vision
- In-Tape, Post Sealing inspection

Specifications subject to change without notice. For detailed performance specifications, please contact Cohu.